Qualcom

RF360 Europe GmbH

SAW components

Micro-acoustic extractor WLAN 2G

Series/type:	B8688
Ordering code:	B39242B8688L210
DCN:	80-PA243-61 Rev. B
Date:	February 02, 2018
Version:	2.2

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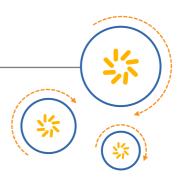
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Micro-acoustic extractor

Data sheet

B8688

699 – 2690 MHz

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699 – 2690 MHz

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1 Application

- High-performance WLAN Extractor with single ended 50 Ω ports.
- Ultra-low-loss acoustic structure.
- Advanced highly-integrated multiplexer structure (no external matching needed).
- Using common antenna for WLAN and Cellular bands.
- Placed between antenna and cellular front-end switches and filters.
- Usable WLAN pass band: 2402.0 2481.5 MHz.
- Usable CELL pass band: 699 960 MHz, 1710 – 2690 MHz.
- No switches and control lines required.

2 Features

- Package size 1.7 mm × 1.3 mm
- Package height 0.6 mm
- Approximate weight 4 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

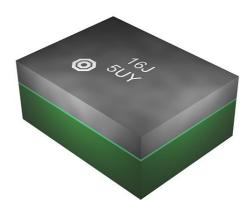


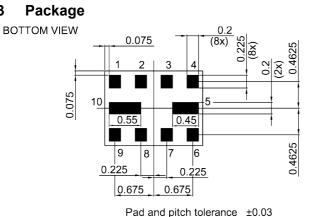
Figure 1: Picture of component with example of product marking.



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3



Pin configuration

- WLAN 1 CELL 4
- **7**, 8 ANT
- **■** 2, 3, 5, 6, Ground 9, 10

(pins 7 and 8 connected on PCB level)

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699 – 2690 MHz

SIDE VIEW

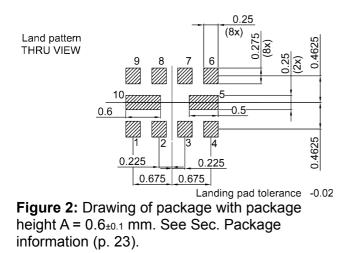
TOP VIEW

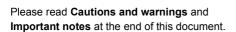
Pad to package edge tolerance ±0.055



<u>1.7±0</u>.1 8 6 7 9 16J 1.3±0.1 10 5UY 3) 2 3 4 2) 1)

- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

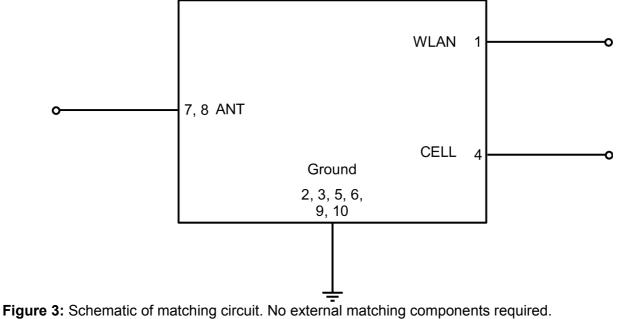




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5 Matching circuit



Antenna pins 7 and 8 have to be directly connected together on PCB level.



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6 Characteristics ANT-WLAN

Temperature range for specification	$T_{_{\rm SPEC}}$	= −30 °C +85 °C
ANT terminating impedance	Z _{ANT}	= 50 Ω
CELL terminating impedance		= 50 Ω
WLAN terminating impedance	Z_{WLAN}	= 50 Ω

Characteristics ANT-WLAN

Characteristics ANT-WLAN				for T_{SPEC}	@ +25 °C	for T_{SPEC}	
Maximum insertion attenuation ¹⁾			α _{max}				
Channel 1	2403.1 2420.9	MHz		—	1.25	2.0 ^{2), 3)}	dB
Channel 2	2408.1 2425.9	MHz		_	1.15	1.9	dB
Channel 3	2413.1 2430.9	MHz		_	1.1	1.9	dB
Channel 4	2418.1 2435.9	MHz		—	1.15	1.9	dB
Channel 5	2423.1 2440.9	MHz		—	1.2	2.0	dB
Channel 6	2428.1 2445.9	MHz		—	1.25	2.1	dB
Channel 7	2433.1 2450.9	MHz		—	1.3	2.2	dB
Channel 8	2438.1 2455.9	MHz		—	1.35	2.3	dB
Channel 9	2443.1 2460.9	MHz		—	1.4	2.4	dB
Channel 10	2448.1 2465.9	MHz		—	1.45	2.4	dB
Channel 11	2453.1 2470.9	MHz		—	1.5	2.4 ^{4), 5)}	dB
Channel 12	2458.1 2475.9	MHz		—	1.65	2.44, 6)	dB
Channel 13	2463.1 2480.9	MHz		—	1.85	2.44,7)	dB
Maximum VSWR			$VSWR_{max}$				
@ ANT port	2403.1 2480.9	MHz		—	1.5	2.14), 8)	
@ WLAN port	2403.1 2480.9	MHz		—	1.6	2.1 ^{4), 9)}	
Minimum attenuation			$\alpha_{_{min}}$				
	699 960	MHz		31	35	_	dB
	1559 1606	MHz		30	35	_	dB
	1710 2025	MHz		31	35	_	dB
	2110 2200	MHz		31	38	_	dB
	2300 2370	MHz	10)	37 ^{4), 11)}	42	_	dB
	2500 2550	MHz	10)	33 ²⁾	41	—	dB
	2550 2690	MHz		35	43	—	dB
	4804 4963	MHz		20	28	—	dB

¹⁾ Average over each WLAN channel with band width of 17.8 MHz. ²⁾ $+25^{\circ}$ C to $+25^{\circ}$ C

²⁾ +25°C to +85°C.

- ³⁾ 2.5dB over temperature range -30°C to +85°C.
- ⁴⁾ +25°C.
- ⁵⁾ 2.6dB over temperature range -30°C to +85°C.
- ⁶⁾ 2.8dB over temperature range -30°C to +85°C.
- ⁷⁾ 3.2dB over temperature range -30°C to +85°C.
- ⁸⁾ 2.5 over temperature range -10° C to $+85^{\circ}$ C.
- ⁹⁾ 2.3 over temperature range -30°C to +85°C.
- ¹⁰⁾ Average over any 5.0 MHz.
- ¹¹⁾ 30dB over temperature range -30°C to +85°C.



min. typ. max.

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7 **Characteristics ANT-CELL**

Temperature range for specification	$T_{_{ m SPEC}}$	= −30 °C +85 °C
ANT terminating impedance	Z _{ANT}	= 50 Ω
CELL terminating impedance	Z _{CELL}	= 50 Ω
WLAN terminating impedance	Z _{WLAN}	= 50 Ω

Characteristics ANT-CELL

Characteristics ANT-CELL				min. for $T_{_{\rm SPEC}}$	typ. @ +25 °C	max. for $T_{\rm SPEC}$	
Maximum insertion attenuation ¹⁾			α _{max}				
	699 960	MHz		_	0.3	0.7	dB
	1559 1606	MHz		_	0.4	0.8	dB
	1710 2025	MHz		_	0.5	1.2	dB
	2110 2170	MHz		_	0.65	1.2	dB
	2300 2370	MHz		—	1.4	2.1 ^{2), 3)}	dB
	2550 2655	MHz		_	1.15	1.7	dB
	2655 2690	MHz		_	1.35	1.9	dB
Maximum VSWR			VSWR _{max}				
@ ANT port	699 960	MHz		_	1.3	1.8	
	1559 1606	MHz		—	1.2	1.8	
	1710 2200	MHz		_	1.3	1.8	
	2300 2370	MHz		_	1.3	2.0	
	2550 2690	MHz		—	1.3	2.0	
@ CELL port	699 960	MHz		_	1.3	1.8	
	1559 1606	MHz		—	1.25	1.8	
	1710 2200	MHz		_	1.3	1.8	
	2300 2370	MHz		—	1.4	2.0	
	2550 2690	MHz		_	1.5	2.1	
Minimum attenuation ⁴⁾			$\alpha_{_{min}}$				
	2403.1 2480.9	MHz		12	15	_	dB

1) Average over any 5.0 MHz.

2) +25°C.

3) 2.9dB over temperature range -30°C to +85°C.

4) Average over each WLAN channel with band width of 17.8 MHz. B8688

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8 Characteristics CELL-WLAN

Temperature range for specification	$T_{_{ m SPEC}}$	= −30 °C +85 °C
ANT terminating impedance	Z _{ANT}	= 50 Ω
CELL terminating impedance	Z _{CELL}	= 50 Ω
WLAN terminating impedance	Z _{WLAN}	= 50 Ω

Characteristics CELL-WLAN				min. for $T_{\rm SPEC}$	typ. @ +25 °C	max. for $T_{_{\rm SPEC}}$	
Isolation			$\alpha_{_{min}}$				
	699 960	MHz		31	34	_	dB
	1559 1606	MHz		30	34	_	dB
	1710 2025	MHz		31	35		dB
	2110 2170	MHz		31	38		dB
	2300 2370	MHz	1)	16	43	_	dB
	2403.1 2480.9	MHz	2)	12	17	_	dB
	2550 2690	MHz		33	41	—	dB

¹⁾ Average over any 5.0 MHz.

²⁾ Average over each WLAN channel with band width of 17.8 MHz.



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9 Maximum ratings

Storage temperature	$T_{\rm STG}^{3)} = -40 {}^{\circ}{\rm C} \dots + 85 {}^{\circ}{\rm C}^{1), 2)}$	
DC voltage	$ V_{\rm DC} = 5.0 \rm V (max.)^4$	
ESD voltage		
	V _{ESD} ⁵⁾ = 100 V (max.)	Machine model.
	V _{ESD} ⁶⁾ = 250 V (max.)	Human body model.
	V _{ESD} ⁷⁾ = 600 V (max.)	Charged device model.
Input power	P _{IN}	
@ WLAN port: 2402.5 2481.5 MHz	24 dBm	19 MHz WLAN signal for 5000 h @ 55 °C.
@ CELL port: 824 849 MHz	33 dBm	GSM signal duty cycle 1:8 for 5000 h @ 55 °C. Effective power in On-state.
@ CELL port: 880 915 MHz	33 dBm	GSM signal duty cycle 1:8 for 5000 h @ 55 °C. Effective power in On-state.
@ CELL port: 1710 1785 MHz	33 dBm	GSM signal duty cycle 1:8 for 5000 h @ 55 °C. Effective power in On-state.
@ CELL port: 1710 2370 MHz	26 dBm	Continuous wave for 5000 h @ 55 °C.
@ CELL port: 1850 1910 MHz	33 dBm	GSM signal duty cycle 1:8 for 5000 h @ 55 °C. Effective power in On-state.
@ CELL port: 2550 2690 MHz	26 dBm	Continuous wave for 5000 h @ 55 °C.

¹⁾ Extended upper limit: 96h@125°C acc. to IEC 60068-2-2-Bb;.

²⁾ Applicable only for components without tape and reel (unpacked).

³⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

⁴⁾ 168h Damp Heat Steady State acc. to IEC60068-2-67 Cy.

⁵⁾ According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

⁶⁾ According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

⁷⁾ According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses.

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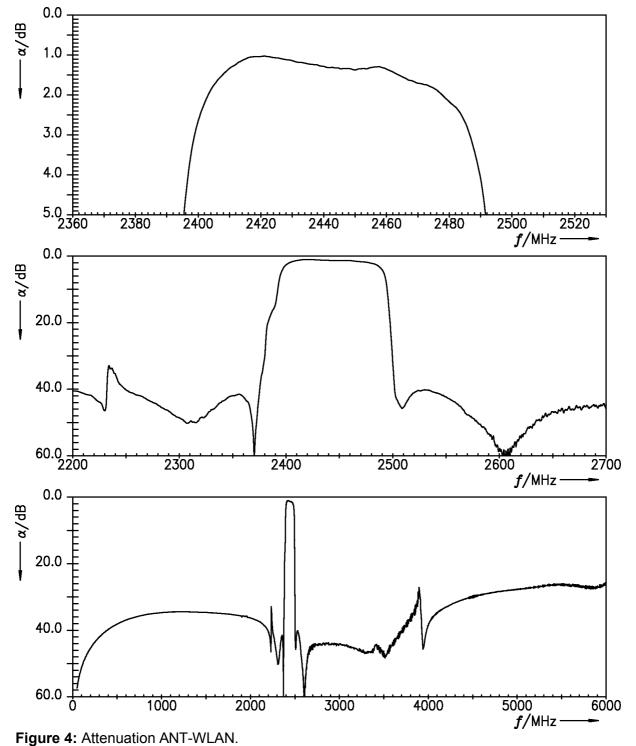
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10 Transmission coefficient ANT-WLAN



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11 Reflection coefficients ANT-WLAN

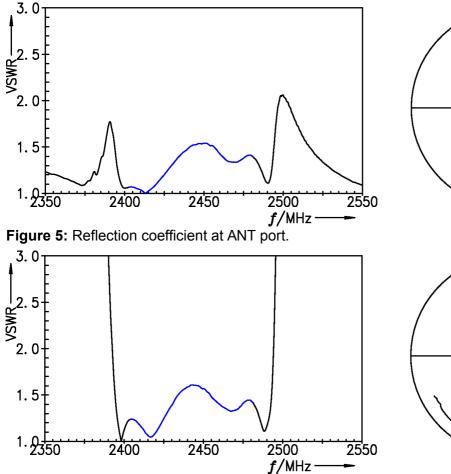
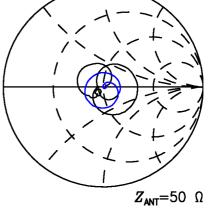
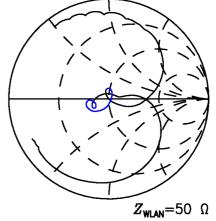


Figure 6: Reflection coefficient at WLAN port.



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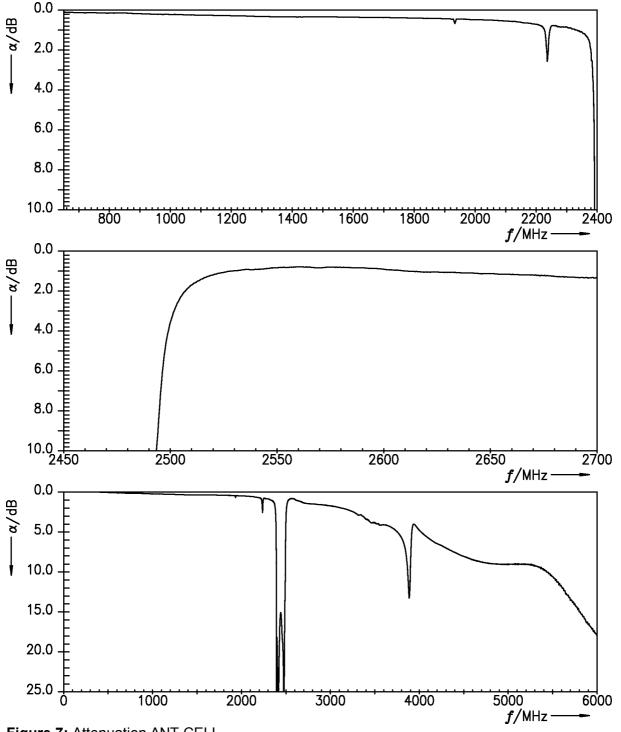


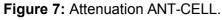


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12 Transmission coefficient ANT-CELL







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13 Reflection coefficients ANT-CELL

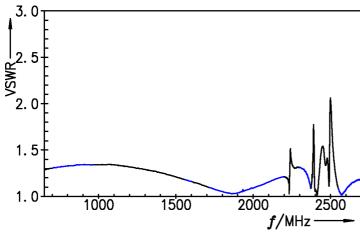
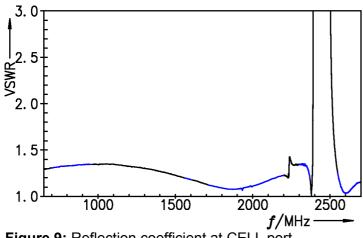
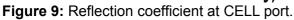


Figure 8: Reflection coefficient at ANT port.







*Z*_{ANT}=50 Ω

 $Z_{\text{CELL}}=50 \ \Omega$

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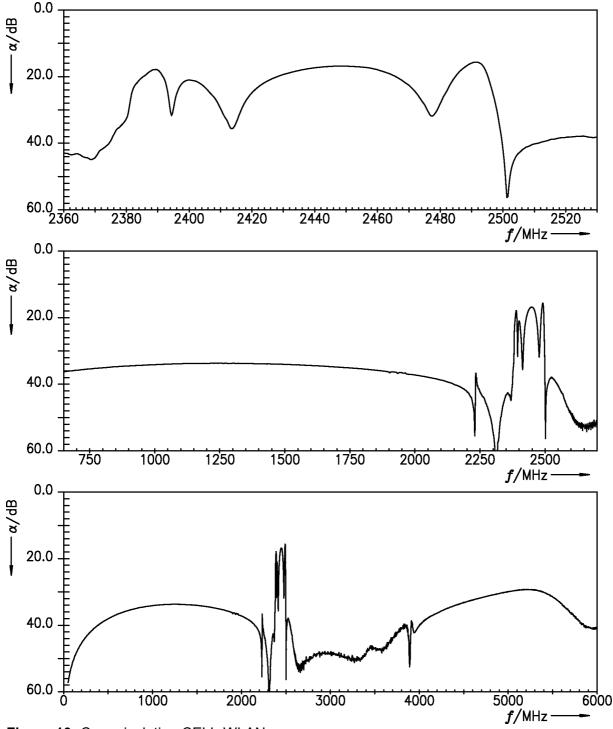
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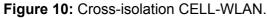
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14 Transmission coefficient CELL-WLAN



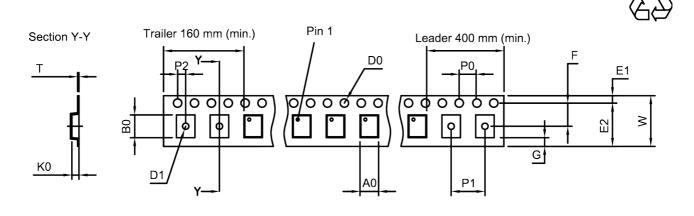


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15 Packing material

15.1 Tape



User direction of unreeling

Figure 11: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A ₀	1.6±0.05 mm
B ₀	2.0±0.05 mm
D ₀	1.5 +0.1/-0 mm
D ₁	0.8 mm (min.)
E1	1.75±0.1 mm

Table 1: Tape dimensions.

E2	6.25 mm (min.)
F	3.5±0.05 mm
G	0.75 mm (min.)
K ₀	0.8±0.05 mm
P ₀	4.0±0.1 mm

P ₁	4.0±0.1 mm
P ₂	2.0±0.05 mm
Т	0.25±0.03 mm
W	8.0+0.3/-0.1 mm

Please read Cautions and warnings and Important notes at the end of this document. Jalco

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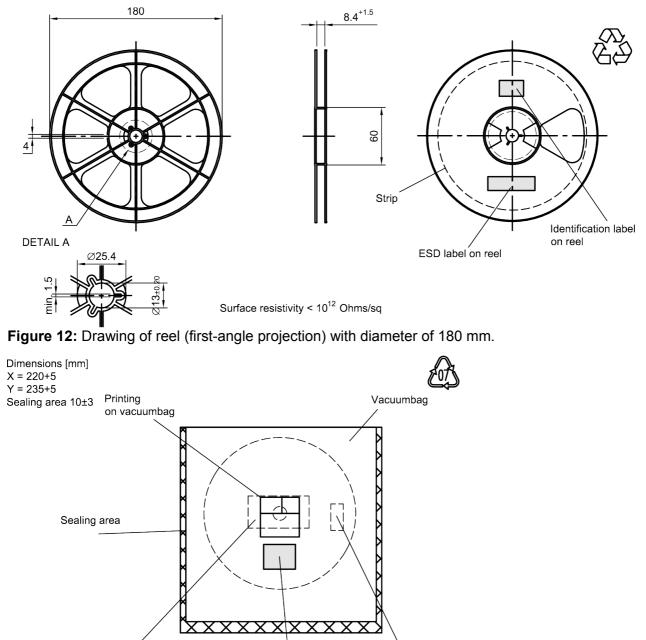
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15.2 Reel with diameter of 180 mm



Drypack
in vacuumbagIdentification label
on vacuumbagHumidity indicator
in vaccumbagFigure 13: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.



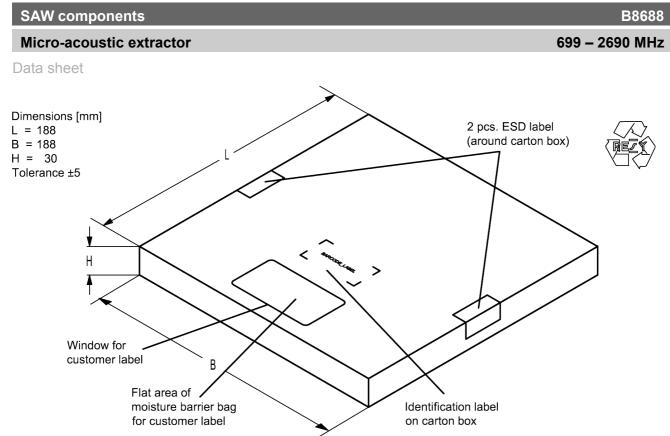
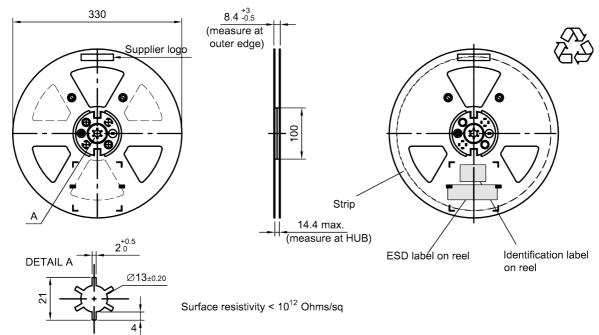
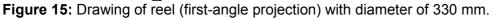


Figure 14: Drawing of folding box for reel with diameter of 180 mm.

15.3 Reel with diameter of 330 mm





Micro-acoustic extractor



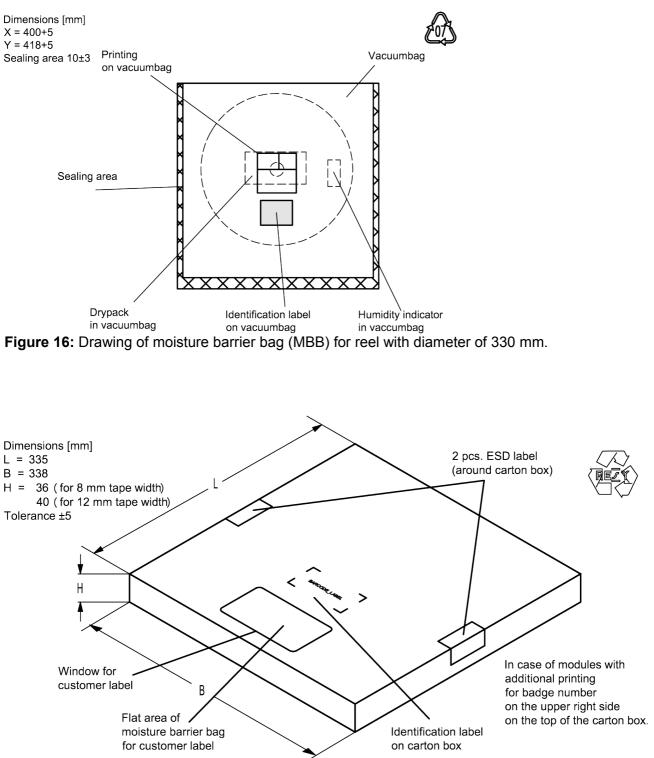


Figure 17: Drawing of folding box for reel with diameter of 330 mm.



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February 02, 2018

1 x 32 ² + 6 x 32 ¹ + 18 (=J) x 32 ⁰	=	1234
The BASE32 code for product type B8688 is 8FG.		
Lot number:		

type number marking on device

■ Lo

Base32

code

G

Н

J

Κ

Μ

Ν

Ρ

Q

R

S

Т

V

W

Х

Y

Ζ

Decimal

value

16

17

18

19

20

21

22

23

24

25

26

27

28

29

30

31

The 4 digit type number of the ordering code,

is encoded by a special BASE32 code into a 3 digit marking.

Adopted BASE47 code for lot number					
Decimal	Base47	Decimal	Base47		
value	code	value	code		
0	0	24	R		
1	1	25	S		
2	2	26	Т		
3	3	27	U		
4	4	28	V		
5	5	29	W		
6	6	30	Х		
7	7	31	Y		
8	8	32	Z		
9	9	33	b		
10	A	34	d		
11	В	35	f		
12	С	36	h		
13	D	37	n		
14	E	38	r		
15	F	39	t		
16	G	40	v		
17	Н	41	١		
18	J	42	?		
19	К	43	{		
20	L	44	}		
21	М	45	<		
22	N	46	>		
23	Р				

Table 2: Lists for encoding and decoding of marking.

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16 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

Decimal

value

0

1

2

3

4

5

6

7

8 9

10

11

12

13 14

15

Example of decoding

16J

Base32

code

0

1

2

3

4

5

6

7

8

9

A

В

С

D

Е

F

Adopted BASE32 code for type number	Adopted BASE4	47 code for lot numb
xample of decoding lot number marking on device 5UY 5 x 47 ² + 27 (=U) x 47 ¹ + 31 (=Y) x 47 ⁰	=> =	in decimal code. 12345 12345
he last 5 digits of the lot number, re encoded based on a special BASE47 code into a 3	e.g., 3 digit marking.	12345,
ot number:		
ne BASE32 code for product type B8688 is 8FG.		

=>

in decimal code.

1234

e.g., B3xxxxB1234xxxx,

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17 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
<i>T</i> > 220 °C	30 s to 70 s
<i>T</i> > 230 °C	min. 10 s
<i>T</i> > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	_
peak temperature T _{peak}	250 °C +0/-5 °C
wetting temperature T _{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

 Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

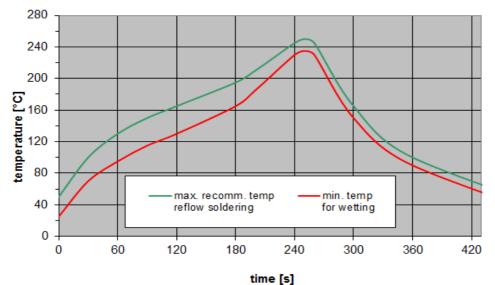


Figure 18: Recommended reflow profile for convection and infrared soldering – lead-free solder.



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18 Annotations

18.1 Matching coils

See TDK inductor pdf-catalog <u>http://www.tdk.co.jp/tefe02/coil.htm#aname1</u> and Data Library for circuit simulation <u>http://www.tdk.co.jp/etvcl/index.htm</u>.

18.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

18.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

18.4 Ordering codes and packing units

Ordering code	Packing unit
B39242B8688L210	15000 pcs
B39242B8688L210S 5	5000 pcs

Table 4: Ordering codes and packing units.

B8688



Micro-acoustic extractor

Data sheet

19 Cautions and warnings

19.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <u>www.rf360jv.com/orderingcodes</u>.

19.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

19.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

19.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.





Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
- 2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
- 3. The warnings, cautions and product-specific notes must be observed.
- 4. In order to satisfy certain technical requirements, some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous). Useful information on this will be found in our Material Data Sheets on the Internet (www.rf360jv.com/material). Should you have any more detailed questions, please contact our sales offices.
- 5. We constantly strive to improve our products. Consequently, the products described in this publication may change from time to time. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also reserve the right to discontinue production and delivery of products. Consequently, we cannot guarantee that all products named in this publication will always be available.

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